[Summary of the Invention]

[Problems to be Solved by the Invention]

[0005]

An object of the present invention is to provide an evaporation material for use in a vacuum deposition method capable of suppressing the bumping phenomenon upon melting the evaporation material.

[Means for Solving the Problems]

[0006]

In order to achieve the foregoing object, the first embodiment of the present invention provides an evaporation material for use in a vacuum deposition method, wherein the evaporation material comprises one or more types among Au, Ag, Pt, Pd and their alloys, micropores are formed on a surface of the evaporation material, and a number of the micropores having an equivalent circle diameter of 0.1 μm or more and 10.0 μm or less is one or more micropores per 500 μm^2. Moreover, the second embodiment of the present invention provides an evaporation material for use in a vacuum deposition method, wherein the evaporation material comprises one or more types among Au, Ag, Pt, Pd and their alloys, and a hydrogen content in the evaporation material is 10 wtppm or less.

[Effect of the Invention]

[0007]

According to the present invention, it is possible to suppress the bumping phenomenon upon melting the evaporation material, and thereby reduce the particles that become adhered on the substrate. Accordingly, the present invention is able to contribute to improving the yield of products.

[Brief Description of the Drawings]

[0008]

[Fig. 1]

Fig. 1 is an image obtained from observing the surface of the evaporation material of Conventional Example 1 using an SEM (5000X).

[Fig. 2]

Fig. 2 is an image obtained from observing the surface of the evaporation material of Example 1-1 using an SEM (5000X).

[Fig. 3]

CLAIMS

[Claim 1]

An evaporation material, wherein the evaporation material comprises one or more types among Au, Ag, Pt, Pd and their alloys, micropores are formed on a surface of the evaporation material, and a number of the micropores having an equivalent circle diameter of 0.1 μm or more and 10.0 μm or less is one or more micropores per 500 μm^2, wherein the evaporation material has a cast structure.

[Claim 2]

The evaporation material according to claim 1, wherein a purity of the evaporation material is 3N (99.9 wt%) or higher.